

Amendments to the Claims

and

Listing of Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Claims 1, 4, 5, 9, and 10 are amended.

Claims 3 and 11 are canceled without prejudice.

1. (currently amended) A semiconductor device comprising:
a die-pad including a first surface and a second surface opposite to the first surface, the second surface including an exposed portion and a retreated portion around the exposed portion;
a semiconductor chip mounted on the first surface of the die-pad; and
a sealing resin covering the die-pad and the semiconductor chip, the resin allowing the exposed portion to be exposed and being held in contact with the retreated portion,
wherein the die-pad is formed with at least one slit that is open in the retreated portion of the second surface and in the first surface.

2. (original) The semiconductor device according to claim 1, wherein the retreated portion is defined by a retreated surface and a side surface which adjoins the exposed portion and forms an acute angle together with the retreated surface.

3. (canceled)

4. (currently amended) The semiconductor device according to claim 1, wherein the die-pad is formed with a plurality of slits that are opened open in the retreated surface of the second surface and in the first surface, the plurality of slits being arranged to surround the semiconductor chip.

5. (currently amended) The semiconductor device according to claim [[3]] 1, wherein the semiconductor chip is electrically connected to the die-pad via a first wire, the first wire being

connected to the first surface of the die-pad at a portion between a peripheral edge of the die-pad and the at least one slit.

6. (original) The semiconductor device according to claim 1, further comprising a terminal electrically connected to the semiconductor chip via a second wire, the terminal being retained by the sealing resin so as to be partially exposed.

7. (original) A semiconductor device comprising: a semiconductor chip; a die-pad including an upper surface on which the semiconductor chip is mounted and a lower surface opposite to the first surface, the die-pad being electrically connected to the semiconductor chip via a first wire; a plurality of leads electrically connected to the semiconductor chip via second wires; and a sealing resin enclosing the semiconductor chip in a manner such that the lower surface of the die-pad is exposed;

wherein the die-pad includes a thin-walled portion formed by removing a part of the lower surface along a peripheral edge of the die-pad, the die-pad being formed with at least one slit extending through the thin-walled portion.

8. (original) The semiconductor device according to claim 7, wherein the sealing resin extends under the thin-walled portion so as not to expose an opening of the slit.

9. (currently amended) The semiconductor device according to claim 8, wherein the at least one slit extends along [[a]] at least one side surface of the semiconductor chip around the semiconductor chip.

10. (currently amended) The semiconductor device according to claim 8, wherein the first wire is connected at one end thereof to the semiconductor chip and connected at another end thereof to the die-pad at a portion between a peripheral edge of the die-pad and the at least one slit.

11. (canceled)